

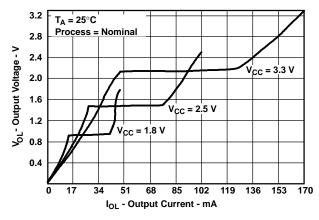
FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Less Than 2-ns Maximum Propagation Delay at 2.5-V and 3.3-V V_{CC}

- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ± 24 mA at 2.5-V V_{CC}
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78. Class II
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

DESCRIPTION

A Dynamic Output Control (DOC^{TM}) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC^{TM}) Circuitry Technology and Applications, literature number SCEA009.



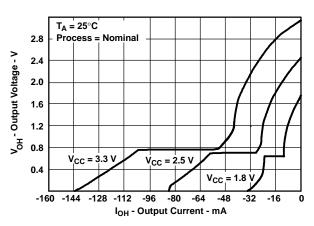


Figure 1. Output Voltage vs Output Current

This 20-bit noninverting buffer/driver is operational at 1.2-V to 3.6-V V_{CC} , but is designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVC16827 is composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable ($1\overline{OE1}$ and $1\overline{OE2}$ or $2\overline{OE1}$ and $2\overline{OE2}$) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16827 is characterized for operation from -40°C to 85°C.



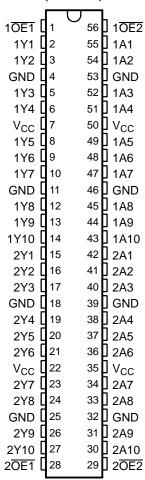
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TERMINAL ASSIGNMENTS

DGG OR DGV PACKAGE (TOP VIEW)



FUNCTION TABLE (EACH 10-BIT BUFFER/DRIVER)

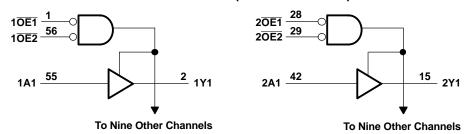
	INPUTS						
OE1	OE2	Α	Y				
L	L	L	L				
L	L	Н	Н				
Н	X	X	Z				
X	Н	Χ	Z				



LOGIC SYMBOL(1) 1 10E1 EN1 56 10E2 28 & 20E1 EN2 29 2OE2 55 2 1 1 ▽ 1Y1 1A1 3 54 1Y2 1A2 5 52 1A3 1Y3 51 6 1A4 1Y4 8 49 1A5 1Y5 48 9 1Y6 1A6 47 10 1A7 1Y7 45 12 1A8 1Y8 44 13 1Y9 1A9 43 14 1Y10 1A10 15 42 2A1 1 2♡ 2Y1 41 16 2A2 2Y2 40 17 2A3 2Y3 38 19 2A4 2Y4 20 37 2Y5 2A5 36 21 2Y6 2A6 34 23 2A7 2Y7 33 24 2A8 2Y8 31 26 2A9 2Y9 30 27 2A10 2Y10

(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



SN74AVC16827 20-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCES176I-DECEMBER 1998-REVISED JUNE 2005



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V_{CC}	Supply voltage range		-0.5	4.6	V	
VI	Input voltage range ⁽²⁾	-0.5	4.6	V		
Vo	Voltage range applied to any output in the high-imp	pedance or power-off state ⁽²⁾	-0.5	4.6	V	
Vo	Voltage range applied to any output in the high or I	-0.5	V _{CC} + 0.5	V		
I _{IK}	Input clamp current	V _I < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through each V _{CC} or GND			±100	mA	
0	Decline the second increase (4)	DGG package		64	00044	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGV package		48	°C/W	
T _{stg}	Storage temperature range	-65	150	°C		

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions

			MIN	MAX	UNIT	
V _{CC}	Supply voltage		1.2	3.6	V	
		V _{CC} = 1.2 V	V _{CC}			
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	$0.65 \times V_{CC}$			
V_{IH}	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.2 V		GND		
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.8		
V_{I}	Input voltage		0	3.6	V	
Vo	Output voltage	Active state	0	V_{CC}	V	
۷٥	Output voltage	3-state	0	3.6	V	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-2		
1	Static high-level output current ⁽¹⁾	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-4	mA	
I _{OHS}	Static high-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	ША	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12		
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		2		
	Static low-level output current ⁽¹⁾	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		4		
I _{OLS}	Static low-level output currents	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8	mA	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		12		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 1.4 \text{ V to } 3.6 \text{ V}$		5	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 3.3-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number SCEA009.

⁽²⁾ The input negative-voltage and output ratings may be exceeded if the input and output current ratings are observed.

³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.

SN74AVC16827



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT	
		$I_{OHS} = -100 \mu A,$	$V_{IH} = V_{CC}$	1.4 V to 3.6 V	V _{CC} - 0.2				
		$I_{OHS} = -2 \text{ mA},$	V _{IH} = 0.91 V	1.4 V	1.05				
V_{OH}	V_{OH}	$I_{OHS} = -4 \text{ mA},$	V _{IH} = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2.3				
		I _{OLS} = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	V _{IL} = 0.49 V	1.4 V			0.4		
V_{OL}		$I_{OLS} = 4 \text{ mA},$	V _{IL} = 0.57 V	1.65 V			0.45	V	
	I _{OLS} = 8 mA,		V _{IL} = 0.7 V	2.3 V			0.55		
		I _{OLS} = 12 mA,	V _{IL} = 0.8 V	3 V			0.7		
I_{\parallel}		$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
I _{off}		V_I or $V_O = 3.6 \text{ V}$		0			±10	μΑ	
I _{OZ}		$V_O = V_{CC}$ or GND,	$V_{IH} = V_{CC}$	3.6 V		±	12.5	μΑ	
I _{CC}		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ	
	Control inputs	V V or CND		2.5 V		4			
	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		4		F	
Ci	Data innuta	V V or CND	V V 0ND			2.5		pF	
	Data inputs	$V_I = V_{CC}$ or GND		3.3 V		2.5			
0	Outpute	V V or CND	V V TO OND			6.5			
C _o	Outputs	$V_O = V_{CC}$ or GND		3.3 V		6.5		pF	

⁽¹⁾ Typical values are measured at $T_A = 25$ °C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2 through Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.2 V	V _{CC} = ± 0.		V _{CC} = ± 0.1		V _{CC} = ± 0.2		V _{CC} = :		UNIT
	(INFOT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y	3	0.4	3.2	0.9	2.9	0.8	1.9	0.5	1.7	ns
t _{en}	ŌĒ	Υ	8.7	2.3	9.1	2.1	8	1.4	5.6	1.2	5.1	ns
t _{dis}	ŌĒ	Υ	7.5	2.7	8.3	2.5	7.3	0.9	4.9	1	4.7	ns

Switching Characteristics⁽¹⁾

 $T_A = 0$ °C to 85°C, $C_L = 0$ pF

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3 ± 0.1	UNIT	
	(IIVFOT)	(001701)	MIN	MAX	
t _{pd}	А	Y	0.09	0.67	ns

⁽¹⁾ Texas Instruments SPICE simulation data

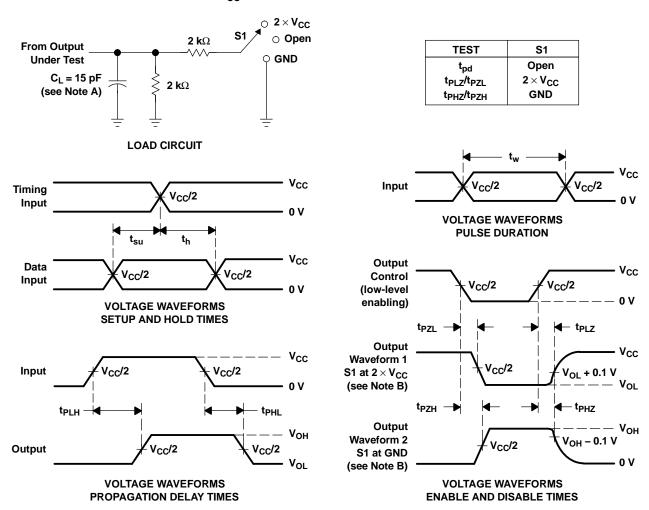
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER			CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
C	Power dissipation	Outputs enabled	C - 0	f = 10 MHz	31	35	40	5E
C_{pd}	capacitance	Outputs disabled	$C_L = 0,$	I = IO WINZ	6	6	6	p⊦



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.2 \text{ V}$ AND 1.5 V \pm 0.1 V

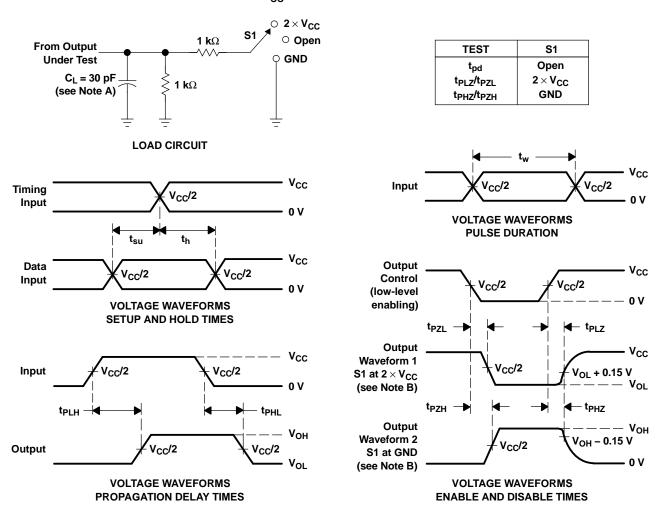


- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 $\Omega,\,t_{f}\leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

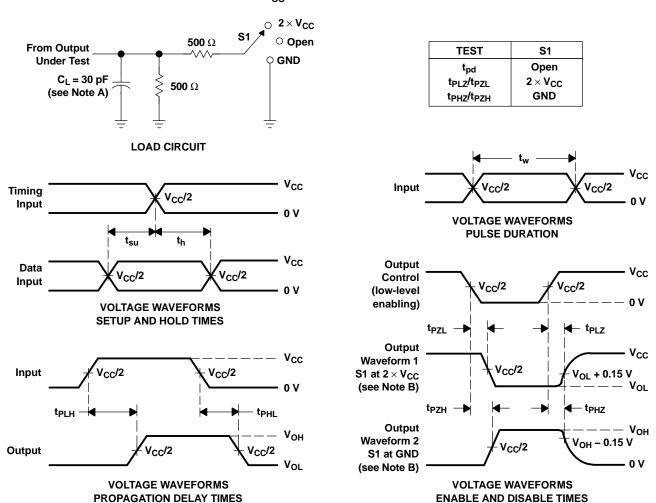


- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 3. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V ± 0.2 V

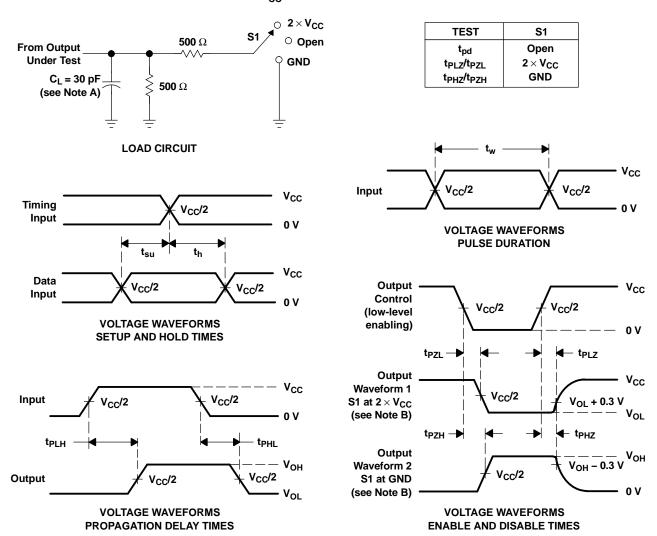


- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 4. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 5. Load Circuit and Voltage Waveforms





com 27-Sep-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AVC16827DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16827DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16827DGVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16827DGVRG4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16827DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16827DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

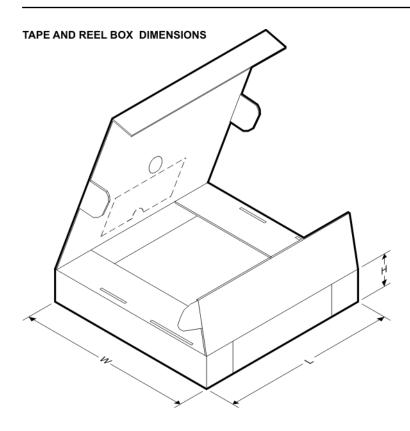
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC16827DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74AVC16827DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC16827DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74AVC16827DGVR	TVSOP	DGV	56	2000	346.0	346.0	41.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

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